IPC ASSOCIATION CONNECT ELECTRONICS INDUSTR	© Copyright 2005. IPC	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both This clevel	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No. Homogeneous Materi					ials and Mfc Information				
upplier Infor	mation								,						
Company name*			Company unique ID			Un	Unique ID Authority					Response Date*			
nsemi											2024-04-24				
Contact Name		,	Title - Contact			Ph	Phone - Contact*				Email - Contact*				
Product-Env-Stev	wards]	Product Enviro Compliance			N/	NA				Product-Env-Stewards@onsemi.com				
uthorized Repre	esentative*	,	Title - Representative			Ph	Phone - Representative*				Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance			N/A	NA				Product-Env-Stewards@onsemi.com				
Reques	Requester Item Number Mfr Item		m Number Mfr Item Name			Ei	ffective Date	Version Manufacturing Site		1	Weight*	UOM	Unit Type		
		NCP1343FNAAABC High Frequence D1R2G Controller		High Frequency Qu Controller	asi-Resonant Flyba	ck 20	2024-04-24 PH1		H1	7	76.13	mg	Each		
I anufacturing	g Proccess Informatio	on													
Terminal Plating / Grid Array Material Terminal Base Allo			Alloy J-S	STD-020 MSL Ratio	-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles						cles				
Matte Tin (Sn) - annealed		CU	CU Alloy 1				260	(2	30	secon	ds 3			
omments															
vel 1 - maximum	ı time at peak temperature	e during sold	ering is 10-3	0 seconds						·		·			
or more informa	tion regarding material co	mposition pl	lease refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.82	mg	Supplier	Silicon (Si)	7440-21-3		1.82	mg
Die Attach Epoxy	0.39	mg		Epoxy resin	proprietary data		0.2535	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		0.1365	mg
Lead Frame	21.32		Supplier	Silver (Ag)	7440-22-4		0.3624	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0256	mg
			Supplier	Iron (Fe)	7439-89-6		0.501	mg
			Supplier	Copper (Cu)	7440-50-8		20.4246	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0064	mg
Mold Compound-Black	51.08			Epoxy resin	proprietary data		2.554	mg
			Supplier	Phenolic Resin	Proprietary Data		1.0216	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		1.277	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2554	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		45.972	mg
Plating	1.37	mg	Supplier	Tin (Sn)	7440-31-5		1.37	mg
Wire Bond - Au	0.15	mg	Supplier	Gold (Au)	7440-57-5		0.15	mg